



## Lockheed Martin TRUST Program Overview:

# A Path to Certified Bonded Aircraft through Bond Process Control

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Lockheed Martin

19 July, 2022

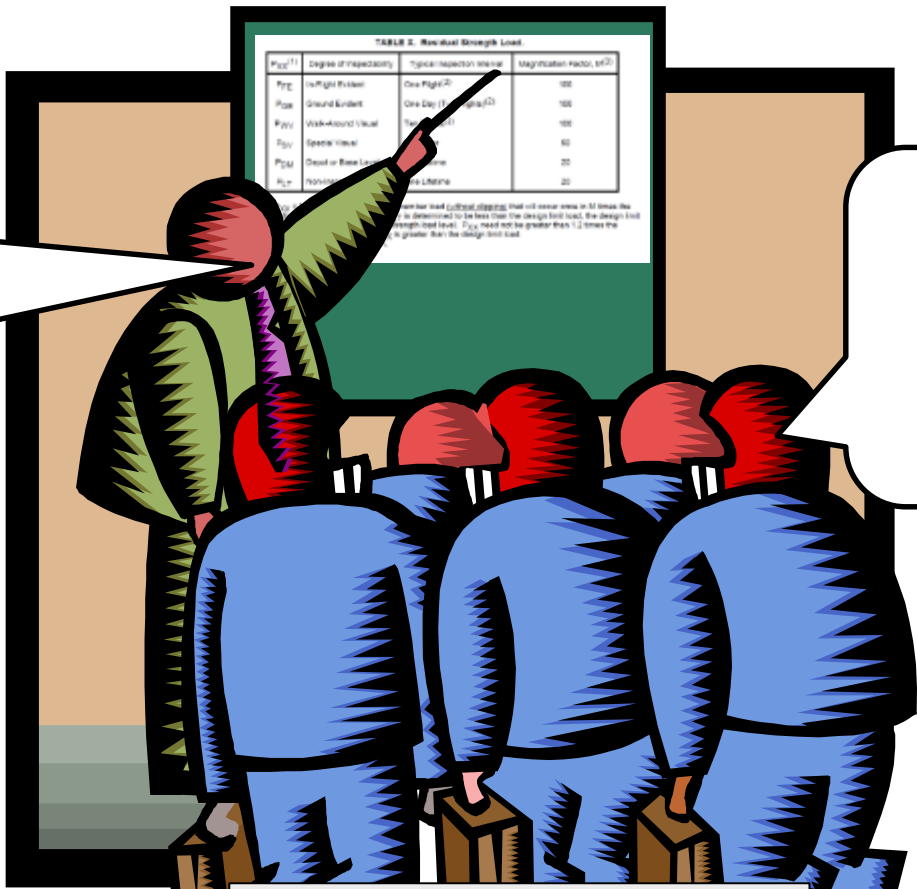
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# Birth of TRUST: Transition to **Reliable Unitized Structure**



Blah Blah  
Blah...**JSSG**  
**Certification of Bonded Structure**...Blah Blah Blah Blah



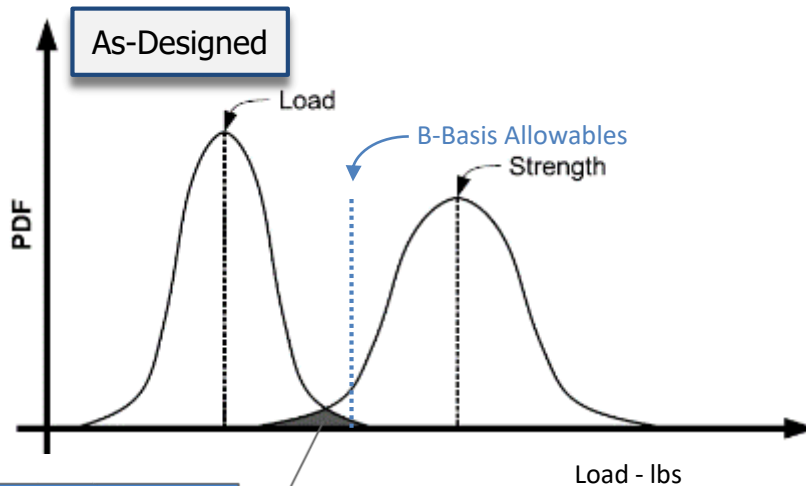
Inspection Type	Degree of Inspection	Typical Inspection Interval	Magnification Factor, $\mu^{(2)}$
Flt	In-Flight Visual	One Flight	100
Flt	Ground Radar	One Day (1 flight)	100
Flt	Walk-around Visual	One Day	100
Flt	Special Visual	As Required	50
Flt	Stand or Bend Load	As Required	20
Flt	Non-destructive Testing	As Required	20

All this talk about Certification assumes you have Process control First!

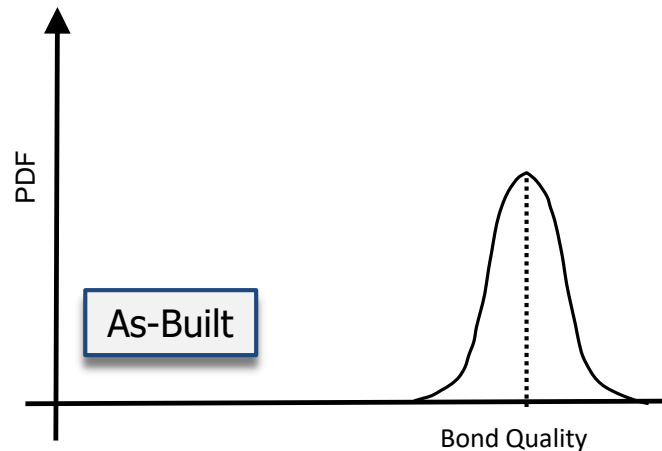
LM Presenting to NAVAIR at Pax River



# TRUST Framework Quantifies Manufacturing Process Reliability, Assuring Engineering Integrity



Intersection is Structural Failure



Process Reliability Protects the Product  
(As-Built  $\geq$  As-Designed)

Traditional Calculation:

$$\text{Strength} \sim F_{(G, E, T, M)}$$

- G: Geometry
- E: Environment
- T: Mfg Tolerances
- M: Material Properties

TRUST Enables:

$$\text{Strength} \sim F_{(G, E, T, M \ \& \ P)}$$

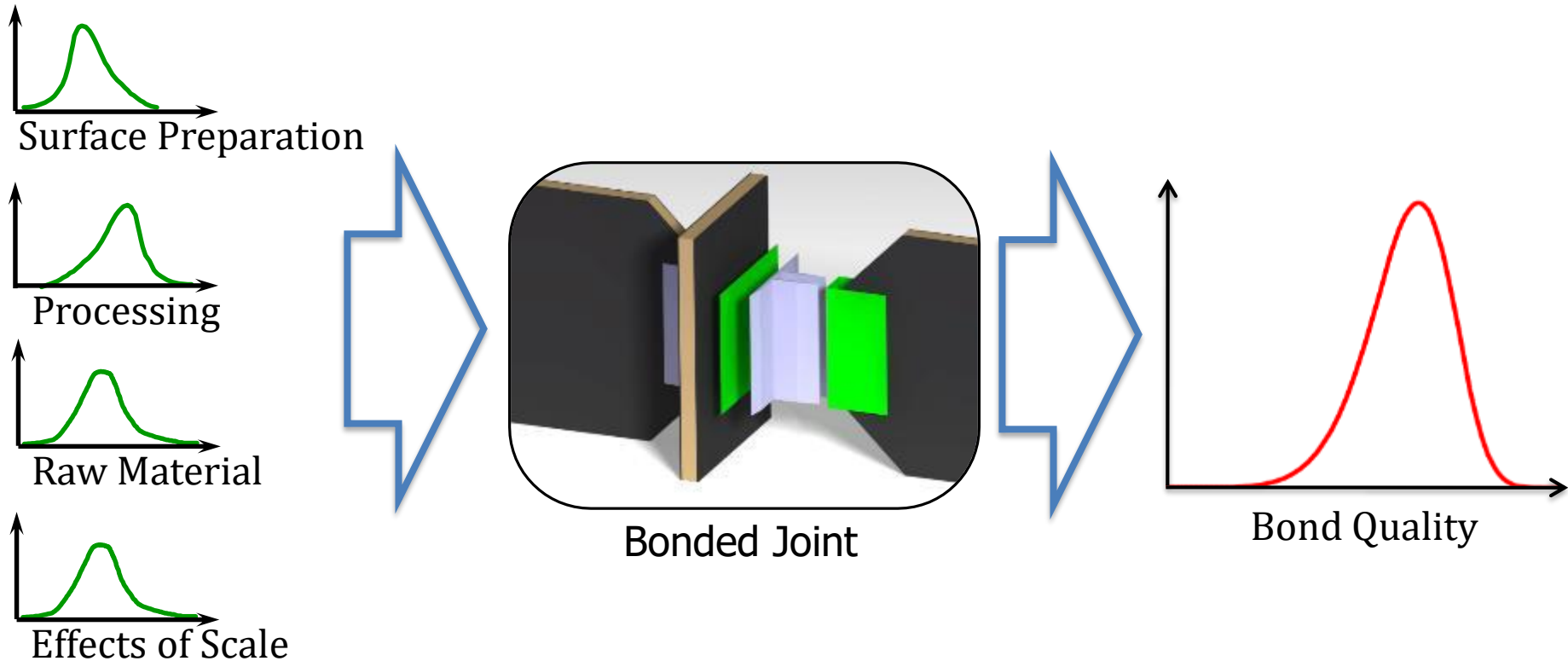
**P: Process Control**



# Quantifying Bond Quality



TRUST Objective: Create a model to predict bond quality



*Reduce and quantify process uncertainty  
Prevent the rogue weak bond*



# Three Phases of TRUST

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## Phase I: Make A Model

**Prove the Ability to  
*Quantify* Bond Reliability**

## Phase II: Develop a Framework

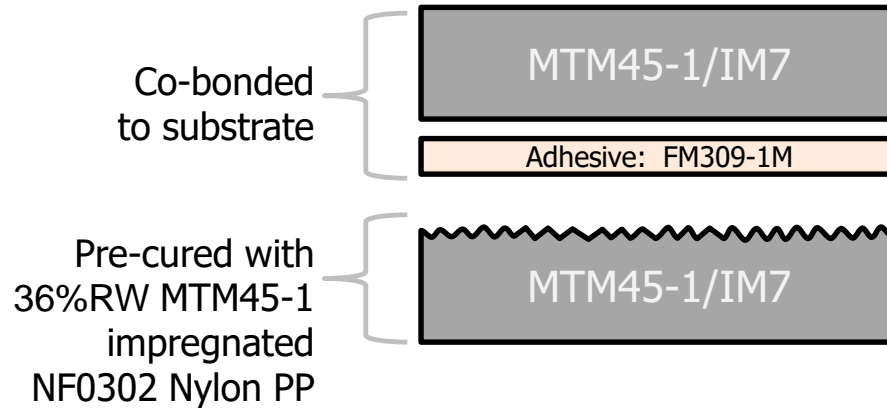
Develop and Mature a Framework to  
*Predict* Bond Quality

## Phase III: Exercise the Framework

*Deliver* A Template For  
Reliable Bonded Structure



# TRUST Materials System



Disclaimer: The TRUST effort was executed on one material system, and the specific conclusions reached may only be applied to that system, however the TRUST approach may be applied to other material systems.

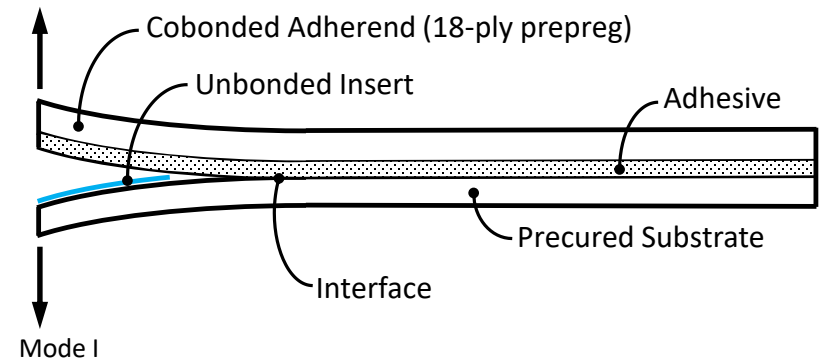


# TRUST Coupon: Double Cantilever Beam (DCB)



- Why DCB?
  - Common test to quantify fracture toughness of bonded structure
  - Mode I “opening mode” fracture very sensitive to bond process
  - Elucidates all relevant failure modes associated with bond quality
- DCB Specimen
  - Pre-cured adherend co-bonded to a green adherend
  - Non-stick insert used to form initial crack

**TRUST DCB Coupon**



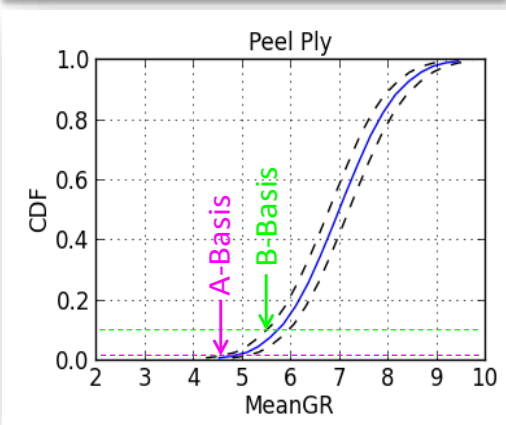
# TRUST Phase I: Bond Process Driven by Data



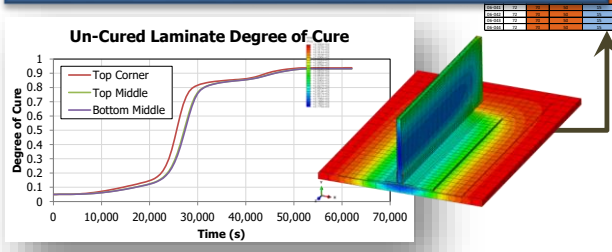
## DCB to DOE & Regression Analysis



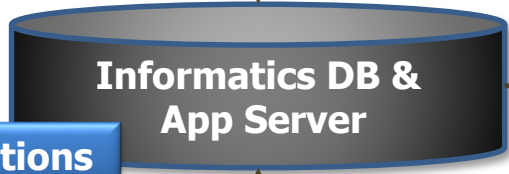
## Linear Regression Model



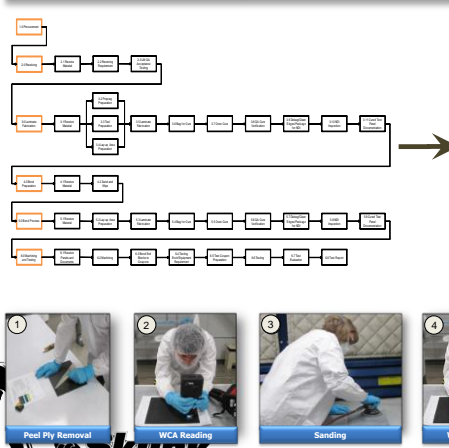
## COMPRO Cure Cycle Modeling



$$f = \beta_0 + \beta_1x_1 + \beta_2x_2 + \beta_3x_3 + \beta_4x_4 + \beta_5x_5 + \beta_6x_6 + \beta_7x_7 + \beta_8x_8 + \beta_9x_9 + \beta_{10}x_{10} + \beta_{11}x_{11} + \beta_{12}x_{12} + \beta_{13}x_{13}^2 + \beta_{14}x_{14}^2 + \beta_{15}x_{15}^2 + \beta_{16}x_{16}^2 + \beta_{17}x_{17}^2 + \beta_{18}x_{18}^2 + \beta_{19}x_{19}^2 + \beta_{20}x_{20}^2 + \beta_{21}x_{21}^2 + \beta_{22}x_{22}^2 + \beta_{23}x_{23}^2 + \beta_{24}x_1x_2 + \beta_{25}x_1x_3 + \beta_{26}x_2x_3 + \beta_{27}x_5x_6 + \beta_{28}x_8x_9 + \beta_{29}x_8x_{10} + \beta_{30}x_9x_{10} + \beta_{31}x_{11}x_{12} + e$$



## Process Map to Electronic Work Instructions



## Automated Device Data Capture






# Three Phases of TRUST

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Prove the Ability to *Quantify*  
Bond Reliability

## Phase II: Develop a Framework

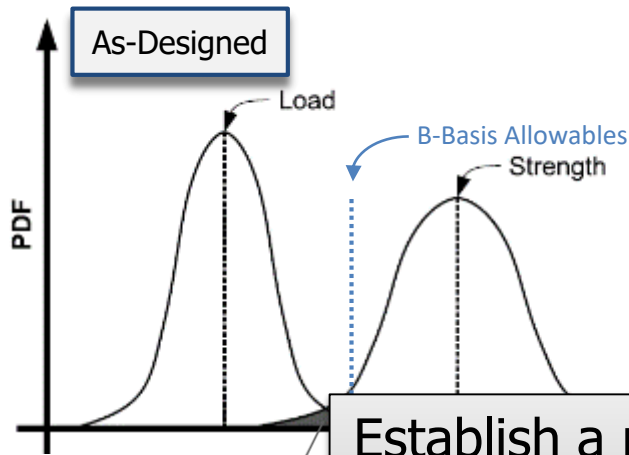
**Develop and Mature a Framework  
to *Predict* Bond Quality**

## Phase III: Exercise the Framework

*Deliver* A Template For  
Reliable Bonded Structure



# TRUST Framework Quantifies Manufacturing Process Reliability, Assuring Engineering Integrity



Traditional Calculation:  
 $Strength \sim F_{(G, E, T, M)}$

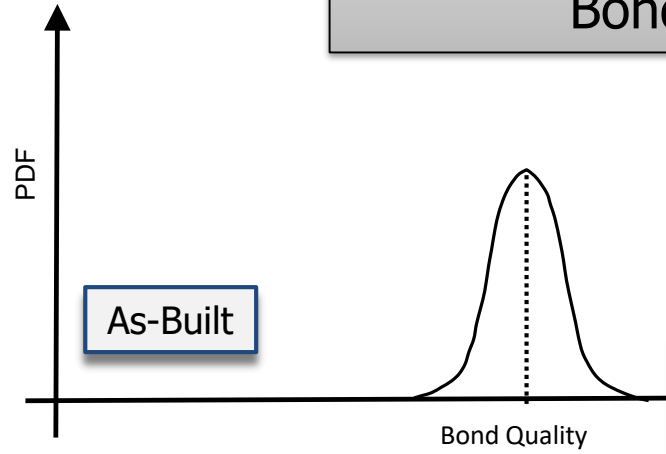
- G: Geometry
- E: Environment
- T: Mfg Tolerances
- M: Material Properties

Examples:  
 $Strength \sim F_{(G, E, T, M \ \& \ P)}$

**P: Process Control**

Establish a relationship between bond process and bond quality... but how do we define Bond Quality?

Intersection is Structural Failure



Process Reliability Protects the Product  
 $(As-Built \geq As-Designed)$



# Bond Quality is a Function of Strength and Failure Mode!

Image Analysis Quantifies the three failure modes present in each coupon.

## Laminate Failure

*Calculated  $G_L = 2.7$  psi-in  
 $X_L$  is Percent of Coupon Surface*

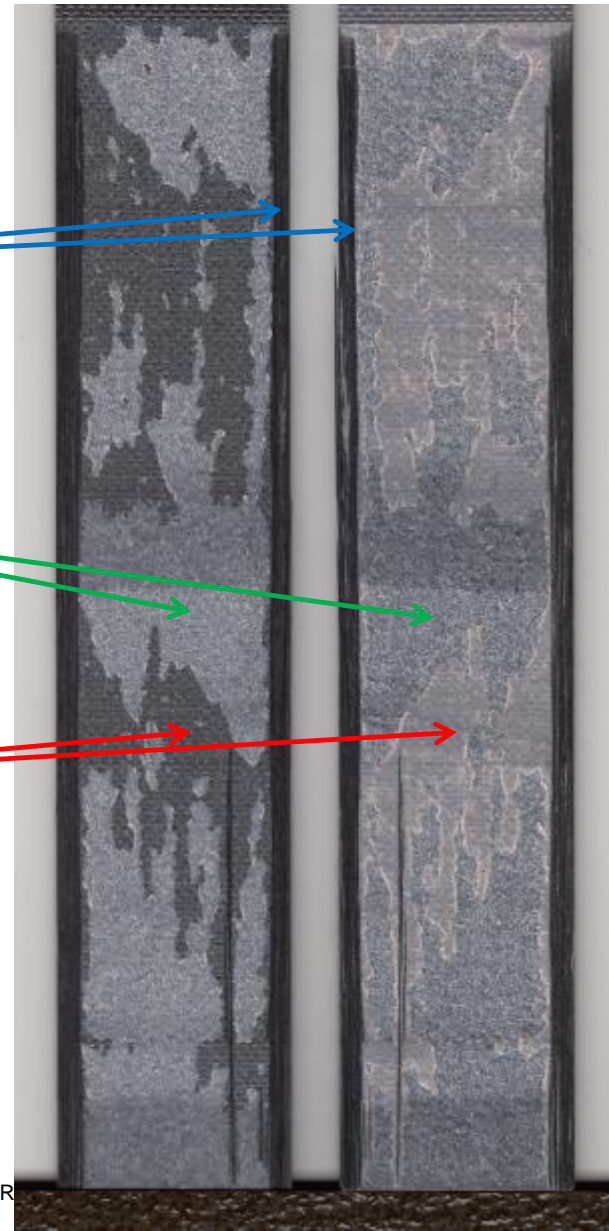
## Cohesive Failure

*Calculated  $G_C = 8.5$  psi-in  
 $X_C$  is Percent Of Coupon Surface*

## Interfacial Failure

*Calculated  $G_I = 3.7$  psi-in  
 $X_I$  is Percent of Coupon Surface*

$$x_L + x_C + x_I = 100\%$$



# Why do we need a Quality Metric?

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- Individually, none of the direct outputs from DCB tests (G, %IF, %LF, %CF) are sufficient to determine good bonds from bad
- A model of G could tell you good bonds are bad
  - Coupons with laminate failure are weaker than those with cohesive failure
- A model of %IF could tell you bad bonds are good
  - A coupon with low interfacial failure could have weak cohesive failure
- We need a way to combine these outputs into a single metric that captures these complexities
  
- What is a good bond?
  - High fracture toughness and low interfacial failure
- What is a bad bond?
  - High interfacial failure
  - Low fracture toughness with high cohesive failure
  
- Two basic questions
  - Given the failure modes, was the bond as tough as expected?
  - Regardless of toughness, was there too much interfacial failure?



# Parallel Deep Dives into Process Details



- Temperature and Humidity Exposure

	Panel No.	% Relative Humidity	Prep to Bond Time (days)	Adhesive Out Time (days)
<b>Nylon Peel Ply, Peel &amp; Stick (NP&amp;S)</b>	12-018	Ambient	0	0
	12-019	40	0	35
	12-020	40	0	50
	12-021	40	15	0
	12-022	40	15	35
	12-023	40	15	50
	12-024	40	25	0
	12-025	40	25	35
	12-026	40	25	50
	12-027	70	0	35
	12-028	70	0	50
	12-029	70	15	0
	12-030	70	15	35
	12-031	70	15	50
	12-032	70	25	0
	12-033	70	25	35
	12-034	70	25	50



# Parallel Deep Dives into Process Details



- Temperature and Humidity Exposure
- Contamination Investigation

CHEMICAL CLASS	Triglyceride	Fatty acid	Long Chain Esters	Alcohol	Surfactant/ Emulsifier	Non-polar Hydrocarbon	Water Soluble Polymer	Silicone/ Fluorocarbon
<b>Archetype Compound</b>	Glyceryl trioleate	Octanoic acid	Glycerol monostearate	Glycerol	Sodium tallowate	Mineral oil	Polyvinyl-pyrrolidone	Dimethyl siloxane
<b>Why We Care</b>	Food	Food, Cosmetics	Cosmetics	Food, Cosmetics	Cutting fluid, lubricants	Lubricants, cosmetics	Cosmetics	Mold release, FEP



# Parallel Deep Dives into Process Details



- Temperature and Humidity Exposure
- Contamination Investigation
- Plasma Automation



# Three Phases of TRUST

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## Phase II: Develop a Framework

Develop and Mature a Framework to  
*Predict* Bond Quality

## Phase III: Exercise the Framework

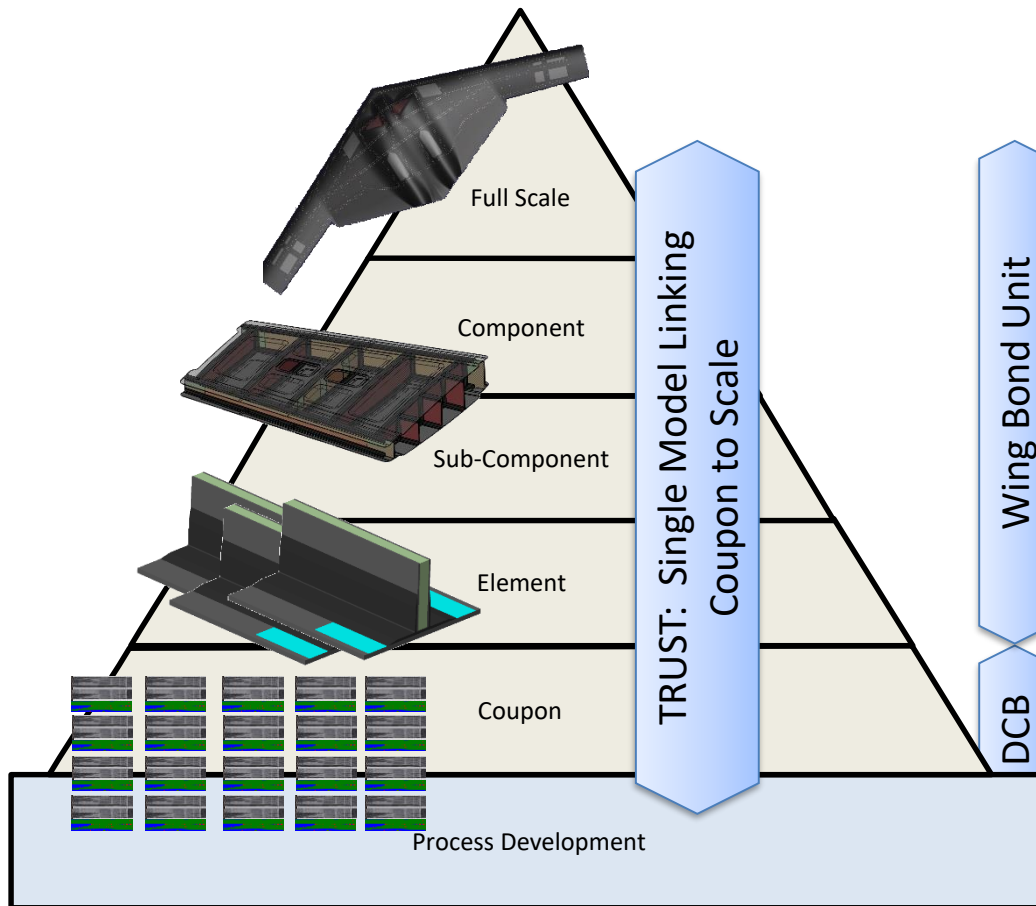
***Deliver A Template For***  
**Reliable Bonded Structure**





# Single Model for Coupon to Article

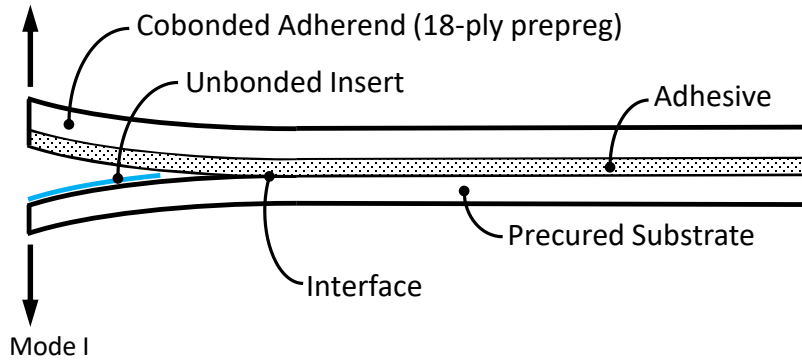
- Phase III goal:  $Q_{DCB} \sim Q_{Wing\ Bond\ Unit}$ 
  - Build on Phase II Model incorporating effects of scale



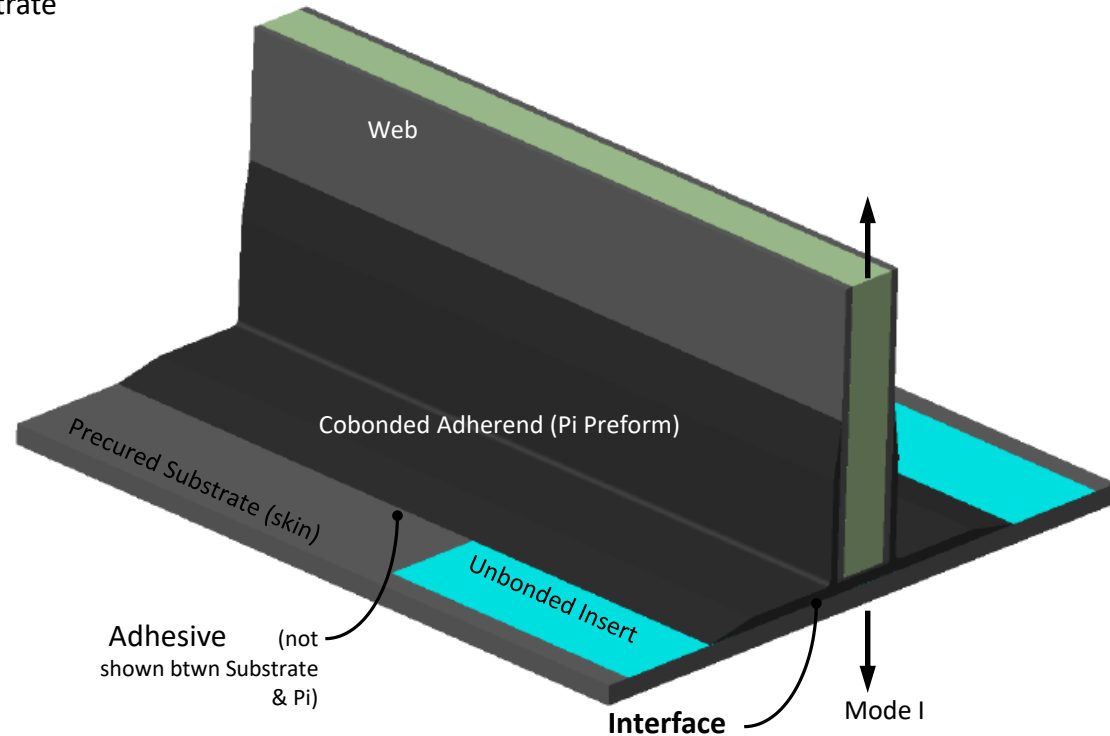
# Scale Up: Build Pi Sticks, Excise and Test Pi-CB



## TRUST DCB Coupon



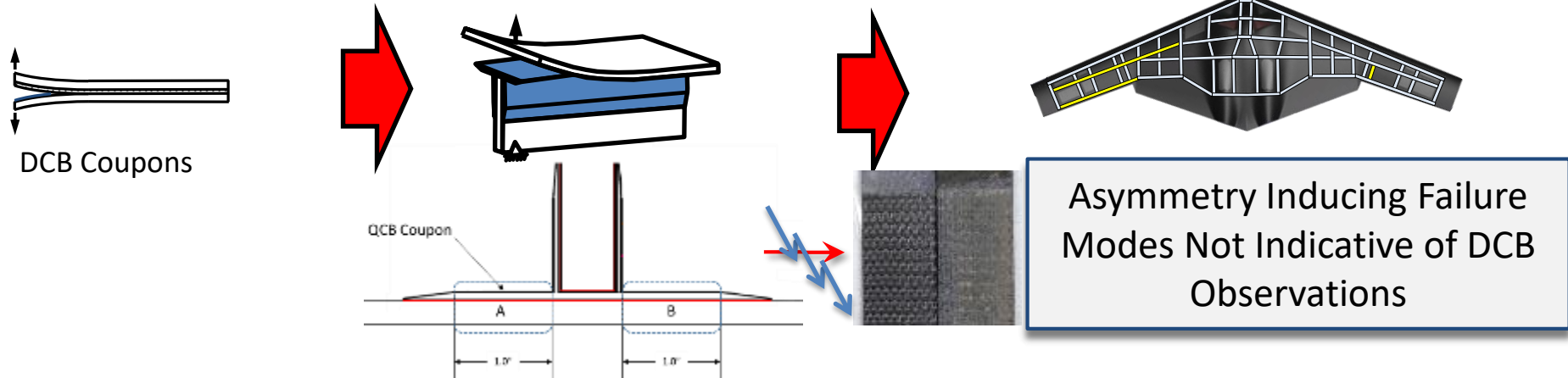
## TRUST Pi-CB Coupon



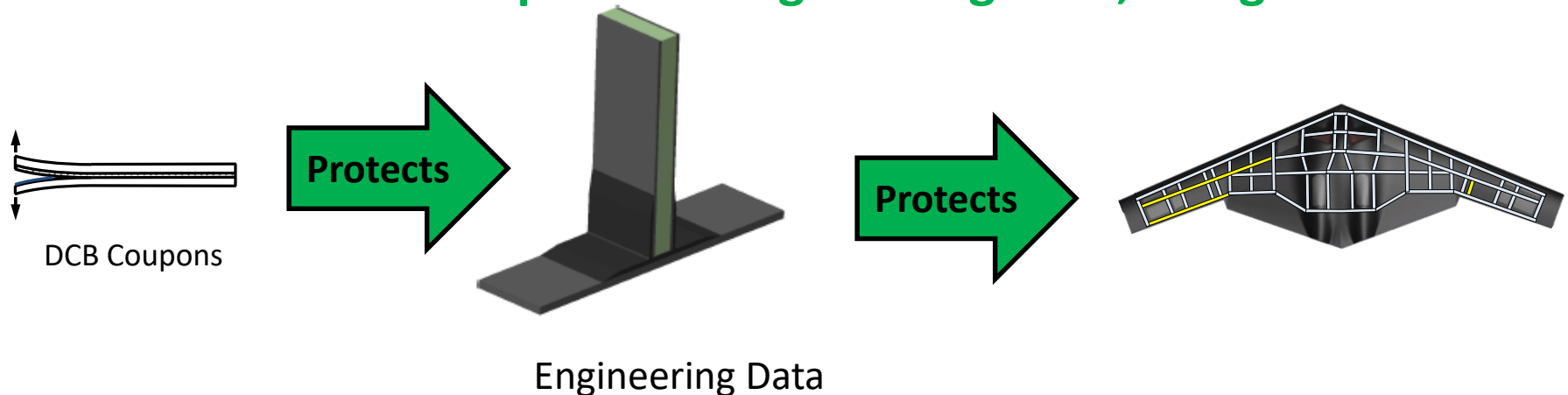
# TRUST Phase III Link from Coupon to Scale



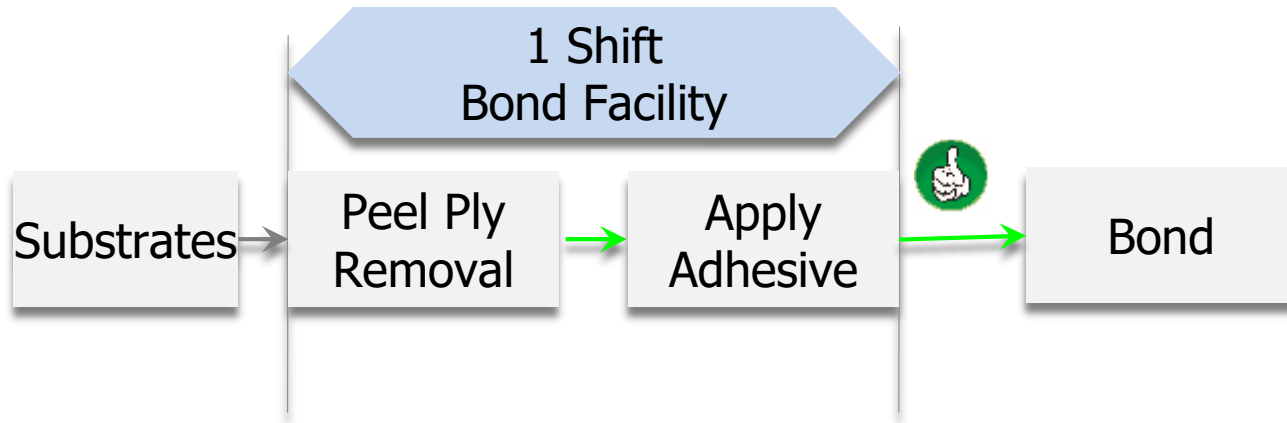
## Pi-CB and QCB are not the link from DCB to Wing Bond Unit



## TRUST Phase III: DCB protects Engineering Data, Wing Bond Unit



# Current State of TRUST Bond Prep



Control It, Peel It, Stick It, Bond It



# Pre-Bond Inspection Devices Evaluated



## BTG Labs Surface Analyst: Water Contact Angle

- Identifies an out-of-spec surface condition
- Sensitive to uppermost  $\sim 0.001\mu\text{m}$  of surface



## X-ray Fluorescence Spectroscopy

- Quantifies the elemental composition of solids, liquids, powders and soils.
- X-rays generated by the x-ray tube bombard the sample
- Photon wavelength identifies element; signal intensity identifies amount



# Develop Handheld Plasma

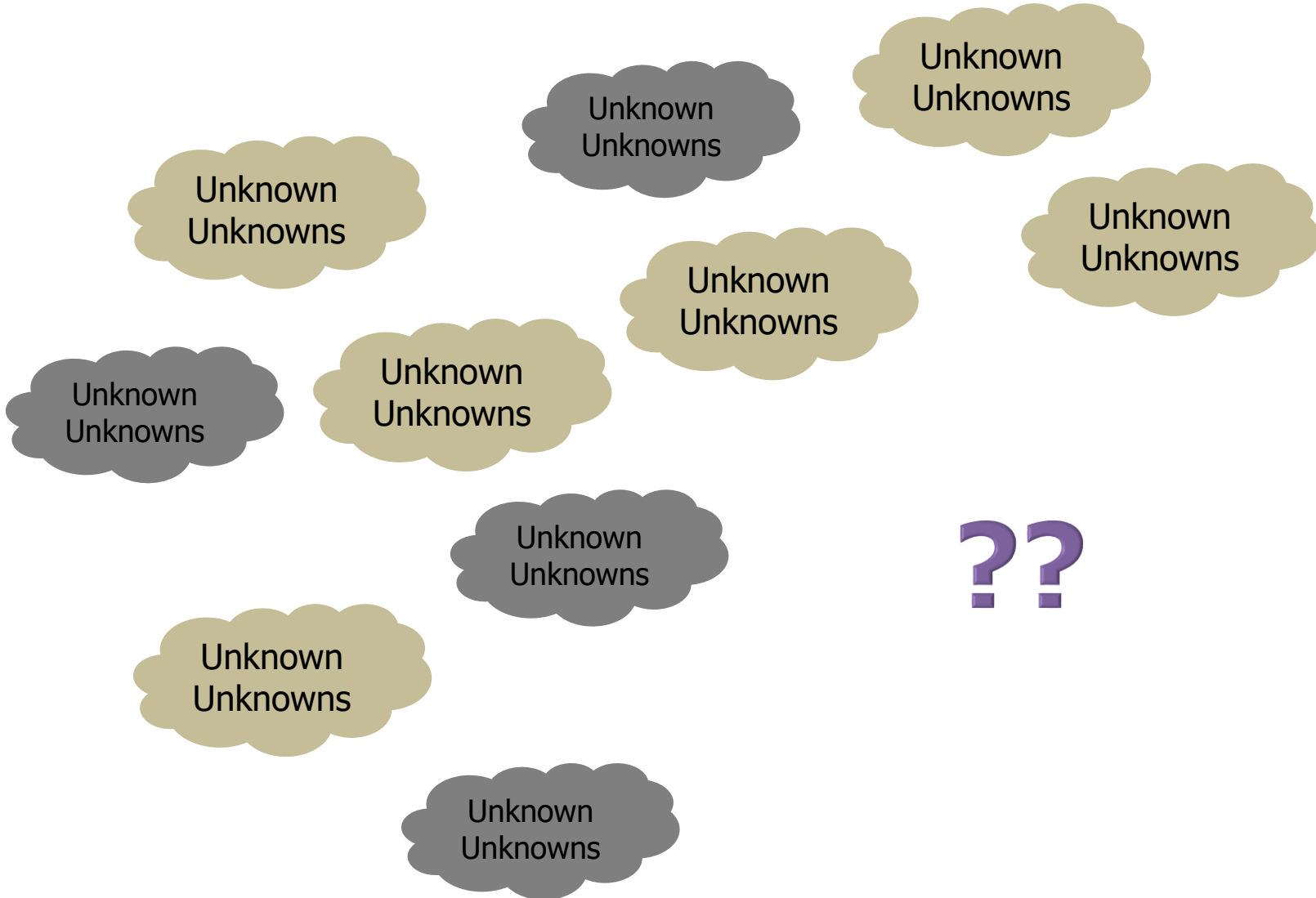
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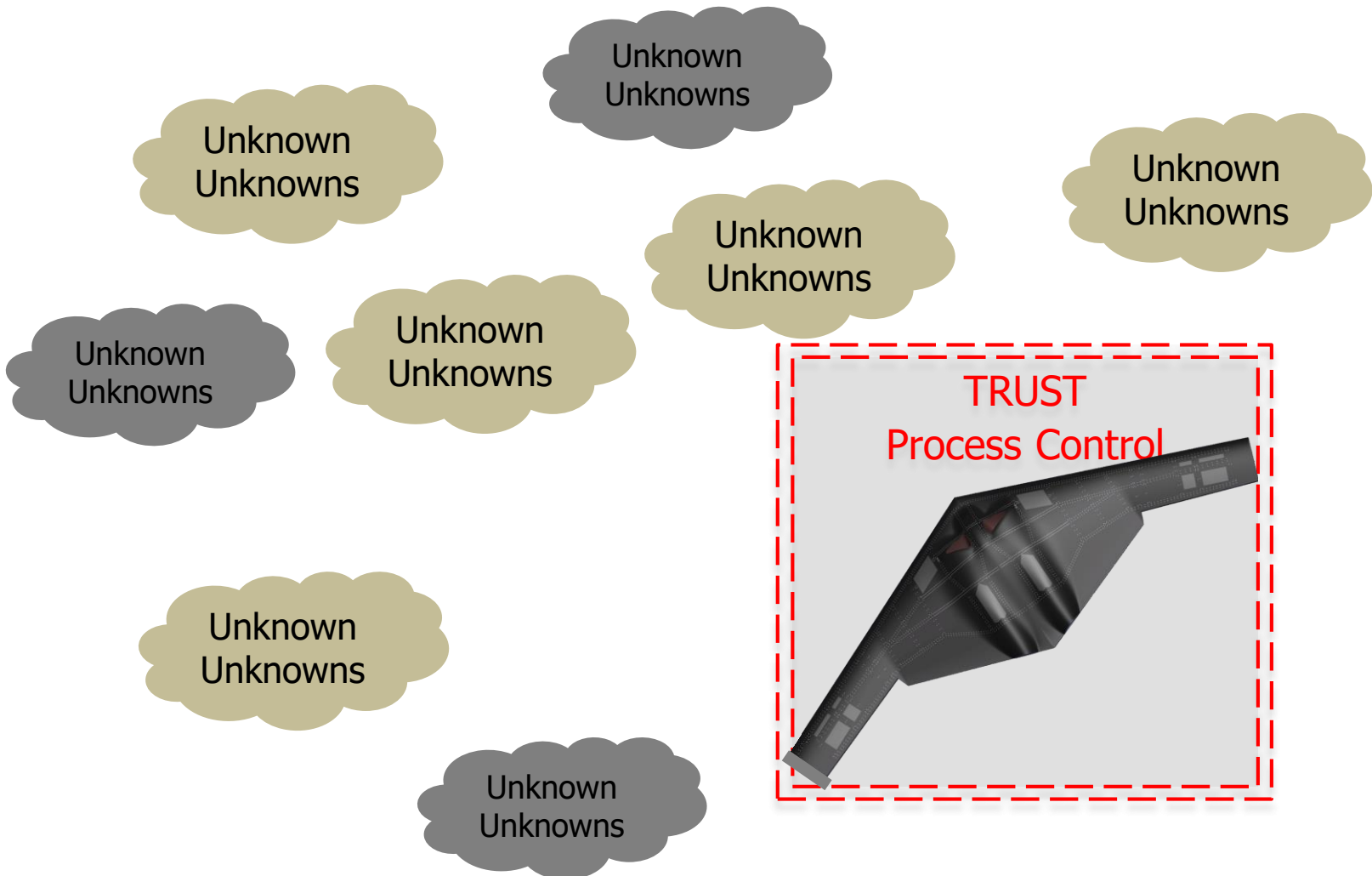
## Intelligent Handheld Plasma Tool IHPT



# Original Bonding State of Knowledge

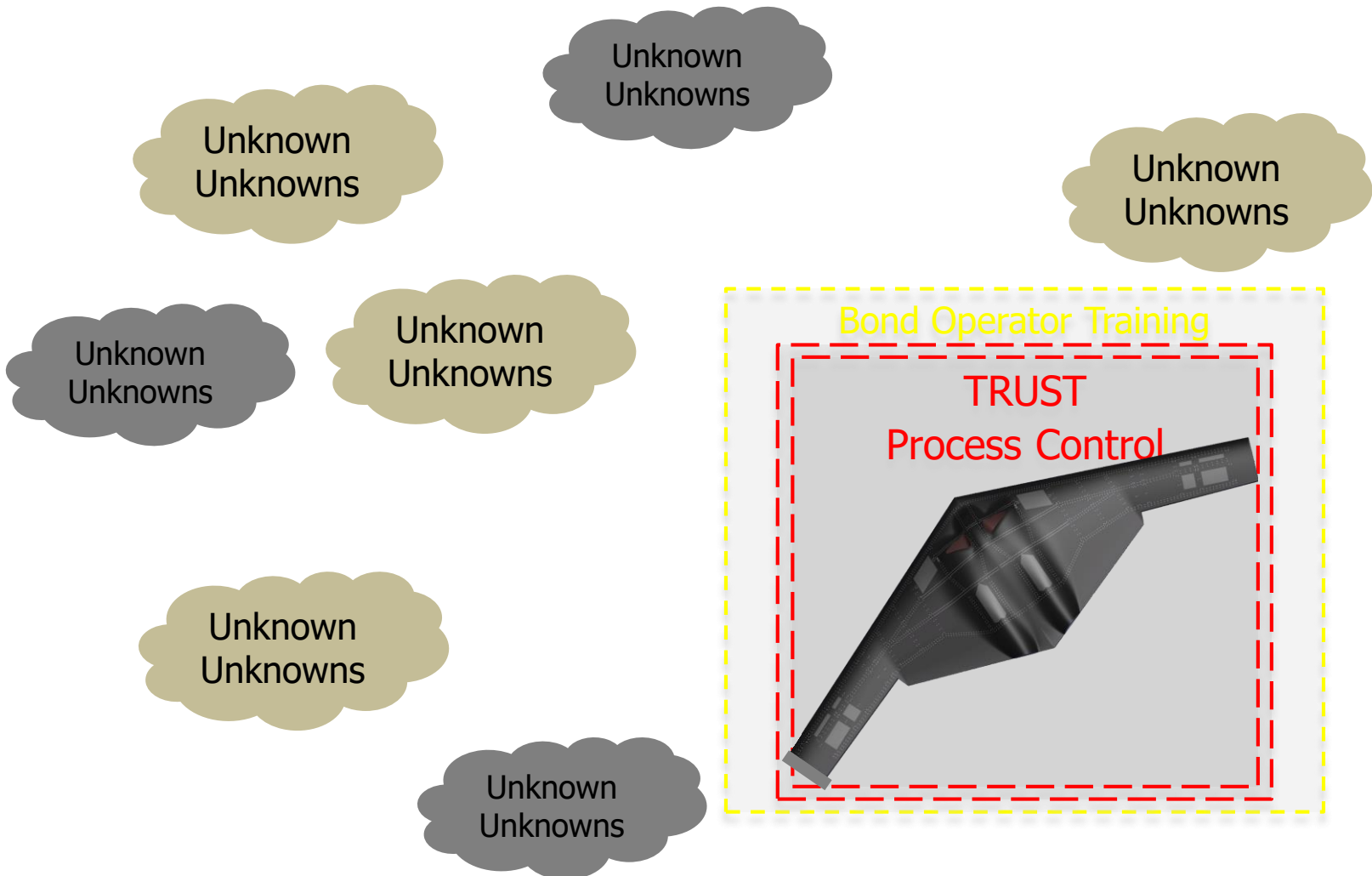


# TRUST Protects "As Designed" & Informs Framework Addressing Unknown Unknowns

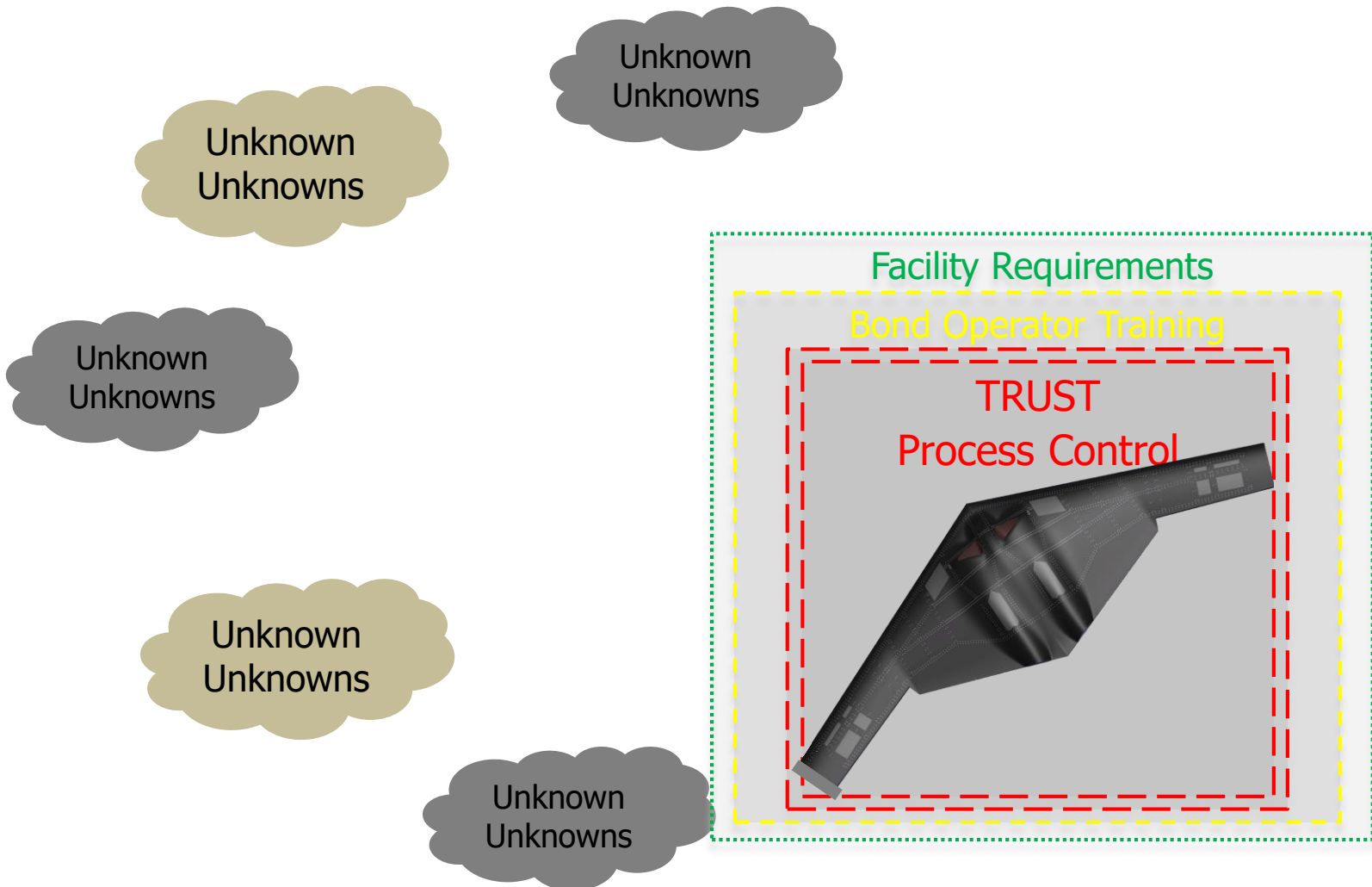




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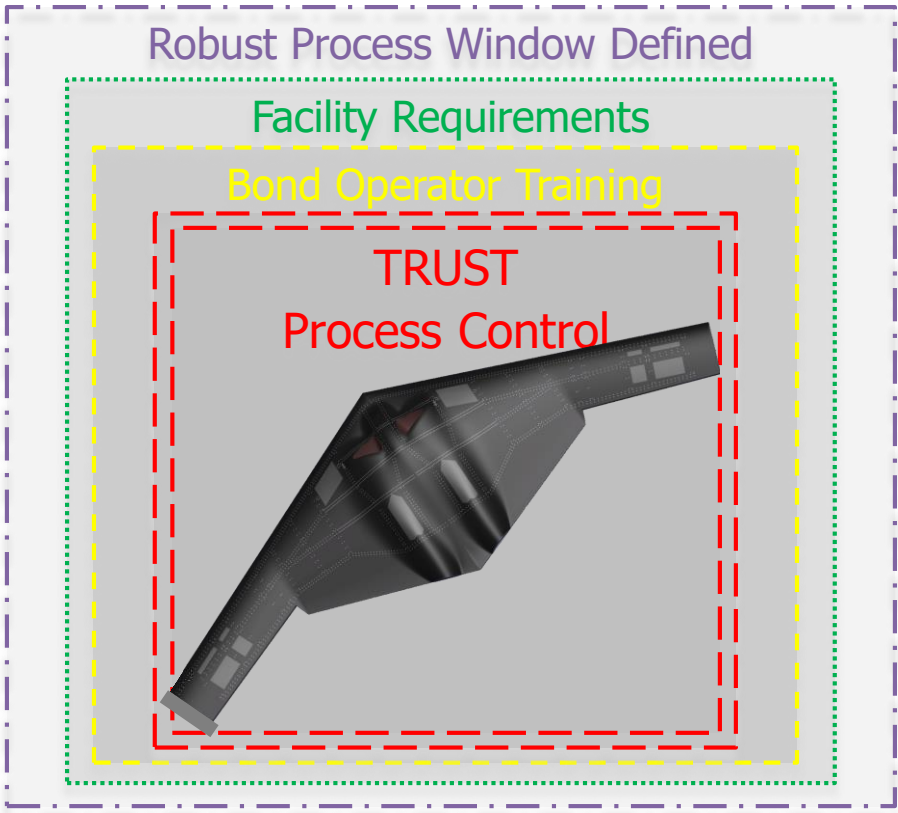
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Unknown Unknowns

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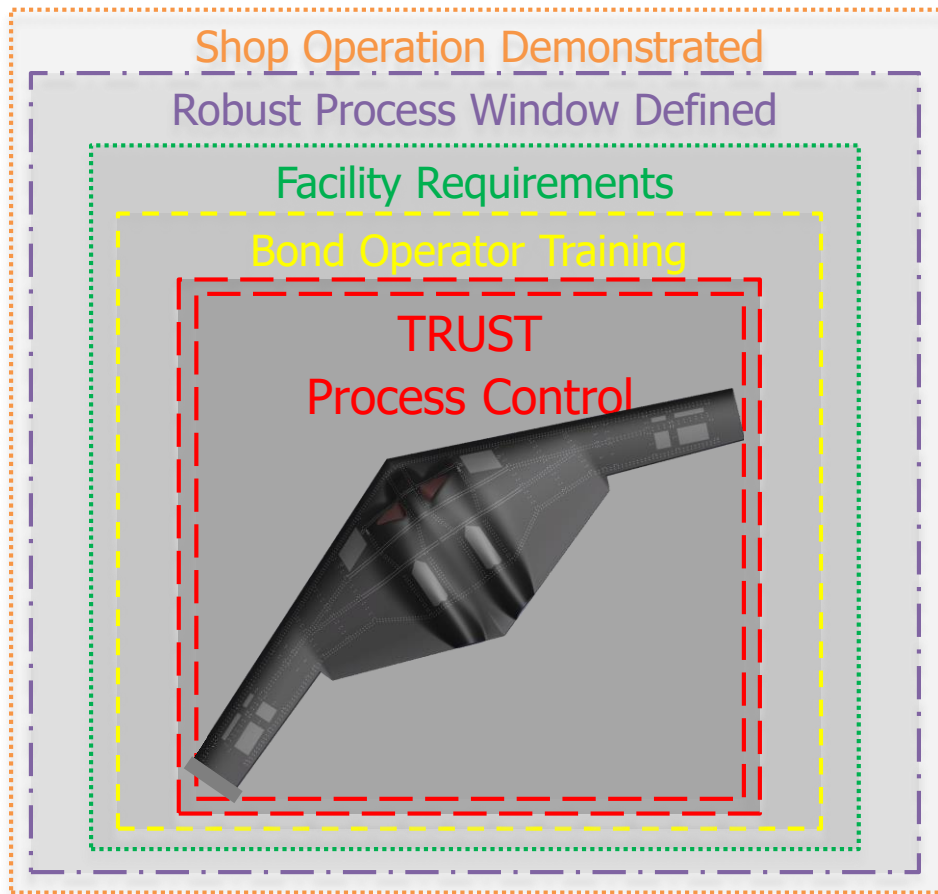
Unknown Unknowns



# TRUST Has Limited the Unk-Unk's



Unknown  
Unknowns



# Acknowledgements

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This research was developed with funding from the Defense Advanced Research Projects Agency (DARPA) and Air Force Research Lab (AFRL-RXM).

Lockheed Martin also wants to recognize our team members who made this happen: BTG Labs, Convergent, Solvay, Southwest Research Inst., and Surfx.



